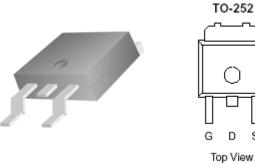
## N-Channel 100-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low  $r_{DS(on)}$  and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

| PRODUCT SUMMARY |                        |          |  |  |
|-----------------|------------------------|----------|--|--|
| $V_{DS}(V)$     | $r_{DS(on)} m(\Omega)$ | $I_D(A)$ |  |  |
| 100             | $280 @ V_{CS} = 10V$   | 11       |  |  |
|                 | $355 @ V_{CS} = 4.5V$  | 10       |  |  |

- Low r<sub>DS(on)</sub> provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe DPAK saves board space
- Fast switching speed
- High performance trench technology





| ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED) |                      |                                   |            |       |
|--------------------------------------------------------------------------|----------------------|-----------------------------------|------------|-------|
| Parameter                                                                |                      |                                   | Limit      | Units |
| Drain-Source Voltage                                                     |                      | $V_{DS}$                          | 100        | v     |
| Gate-Source Voltage                                                      |                      |                                   | ±20        |       |
| Continuous Drain Current <sup>a</sup>                                    | T <sub>C</sub> =25°C | $I_D$                             | 11         |       |
| Pulsed Drain Current <sup>b</sup>                                        |                      |                                   | 36         | A     |
| Continuous Source Current (Diode Conduction) <sup>a</sup>                |                      |                                   | 30         | Α     |
| Power Dissipation <sup>a</sup>                                           | Tc=25°C              | $P_{\mathrm{D}}$                  | 50         | W     |
| Operating Junction and Storage Temperature Range                         |                      | T <sub>J</sub> , T <sub>stg</sub> | -55 to 175 | °C    |

| THERMAL RESISTANCE RATINGS               |                |         |       |  |
|------------------------------------------|----------------|---------|-------|--|
| Parameter                                | Symbol         | Maximum | Units |  |
| Maximum Junction-to-Ambient <sup>a</sup> | $R_{	heta JA}$ | 50      | °C/W  |  |
| Maximum Junction-to-Case                 | $R_{	heta JC}$ | 3.0     | °C/W  |  |

1

## Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

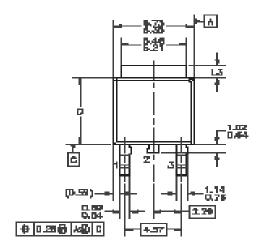
| SPECIFICATIONS (T <sub>A</sub> = 25°C UNLESS OTHERWISE NOTED) |                     |                                                                         |        |      |     |       |  |
|---------------------------------------------------------------|---------------------|-------------------------------------------------------------------------|--------|------|-----|-------|--|
| Danis - 4                                                     | Ch al               | T G 1111                                                                | Limits |      |     | TT *4 |  |
| Parameter                                                     | Symbol              | Test Conditions                                                         | Min    | Тур  | Max | Unit  |  |
| Static                                                        | •                   |                                                                         | •      |      |     |       |  |
| Gate-Threshold Voltage                                        | $V_{GS(th)}$        | $V_{\mathrm{DS}} = V_{\mathrm{GS}},  I_{\mathrm{D}} = 250  \mathrm{uA}$ | 1.0    |      |     | V     |  |
| Gate-Body Leakage                                             | Igss                | $V_{DS} = 0 \text{ V}, V_{GS} = 20 \text{ V}$                           |        |      | ±10 | μA    |  |
| Zero Gate Voltage Drain Current                               | I <sub>DSS</sub>    | $V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$                           |        |      | 1   | ^     |  |
| Zero Gate Voltage Diani Current                               | IDSS                | $V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^{\circ}\text{C}$ |        |      | 25  | μA    |  |
| On-State Drain Current <sup>A</sup>                           | I <sub>D(on)</sub>  | $V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$                           | 34     |      |     | A     |  |
| D : G . C . D : A                                             |                     | $V_{GS} = 10 \text{ V}, I_D = 4.5 \text{ A}$                            |        |      | 280 | mΩ    |  |
| Drain-Source On-Resistance <sup>A</sup>                       | rDS(on)             | $V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$                             |        |      | 355 |       |  |
| Forward Tranconductance <sup>A</sup>                          | gfs                 | $V_{DS} = 15 \text{ V}, I_{D} = 4.5 \text{ A}$                          |        | 5    |     | S     |  |
| Diode Forward Voltage                                         | $V_{\mathrm{SD}}$   | $I_S = 9 A, V_{GS} = 0 V$                                               |        | 1    |     | V     |  |
| Dynamic <sup>b</sup>                                          |                     |                                                                         |        |      |     |       |  |
| Total Gate Charge                                             | Qg                  | $V_{DS} = 50 \text{ V}, V_{GS} = 5.5 \text{ V},$                        |        | 10   |     |       |  |
| Gate-Source Charge                                            | Qgs                 | VDS = 50  V, VGS = 5.5  V, $ID = 4.5  A$                                |        | 2    |     | nC    |  |
| Gate-Drain Charge                                             | Qgd                 | ID = 4.5  A                                                             |        | 7.8  |     |       |  |
| Turn-On Delay Time                                            | t <sub>d(on)</sub>  |                                                                         |        | 4.8  |     |       |  |
| Rise Time                                                     | t <sub>r</sub>      | $V_{\rm DD} = 50$ V, $R_{\rm L} = 11.1~\Omega$ ,                        |        | 4    |     | nS    |  |
| Turn-Off Delay Time                                           | t <sub>d(off)</sub> | $I_D = 4.5 A$ , $V_{GEN} = 10 V$                                        |        | 12.8 |     | 113   |  |
| Fall-Time                                                     | tf                  |                                                                         |        | 4    |     | [     |  |

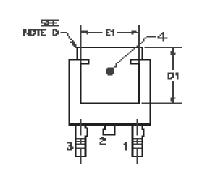
## Notes

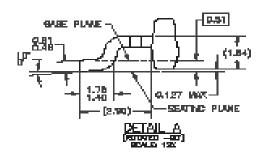
- a. Pulse test:  $PW \le 300$ us duty cycle  $\le 2\%$ .
- b. Guaranteed by design, not subject to production testing.

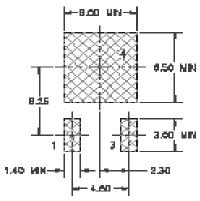
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## Package Information

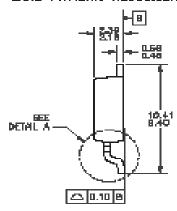








LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- ALL DIPERSONS ARE IN INCLINETERS.
  THIS PRODUCE CONFORMS TO JEDEC, TO-262,
  188UE C, VARIATION AS IN 68, DATED NOW 1989.
  DIMENSIONING AND TOLERANGING PER
- MANE THANH-1884.
  HEAT SINK TOP EDGE COULD BE IN CHANFERED
  CORRESS OR EDGE PROTRUSION.
  DIMENSIONS 13,0,61401 TABLE:

|   | OPTION JAI | Carrell Assess |  |  |
|---|------------|----------------|--|--|
|   | 0.0 -1.27  | 1.82-7.00      |  |  |
|   |            | 8.44-8.40      |  |  |
|   | 4.42       | 310 J Y H      |  |  |
| п |            | 4.47           |  |  |